

ABSTRACT OF THE DISCLOSURE

In a lead frame, a die-pad portion is defined for a semiconductor element to be mounted, a plurality of wire bonding portions are arranged along a periphery of the die-pad portion within a region to be finally divided as a semiconductor device for the die-pad portion, and a plurality of land-like external terminal portions are arranged in a region outside the wire bonding portions. Furthermore, a plurality of linear connection lead portions are formed to integrally join the wire bonding portions to the respective corresponding external terminal portions. The die-pad portion, the wire bonding portions, the external terminal portions and the connection lead portions are supported by an adhesive tape.